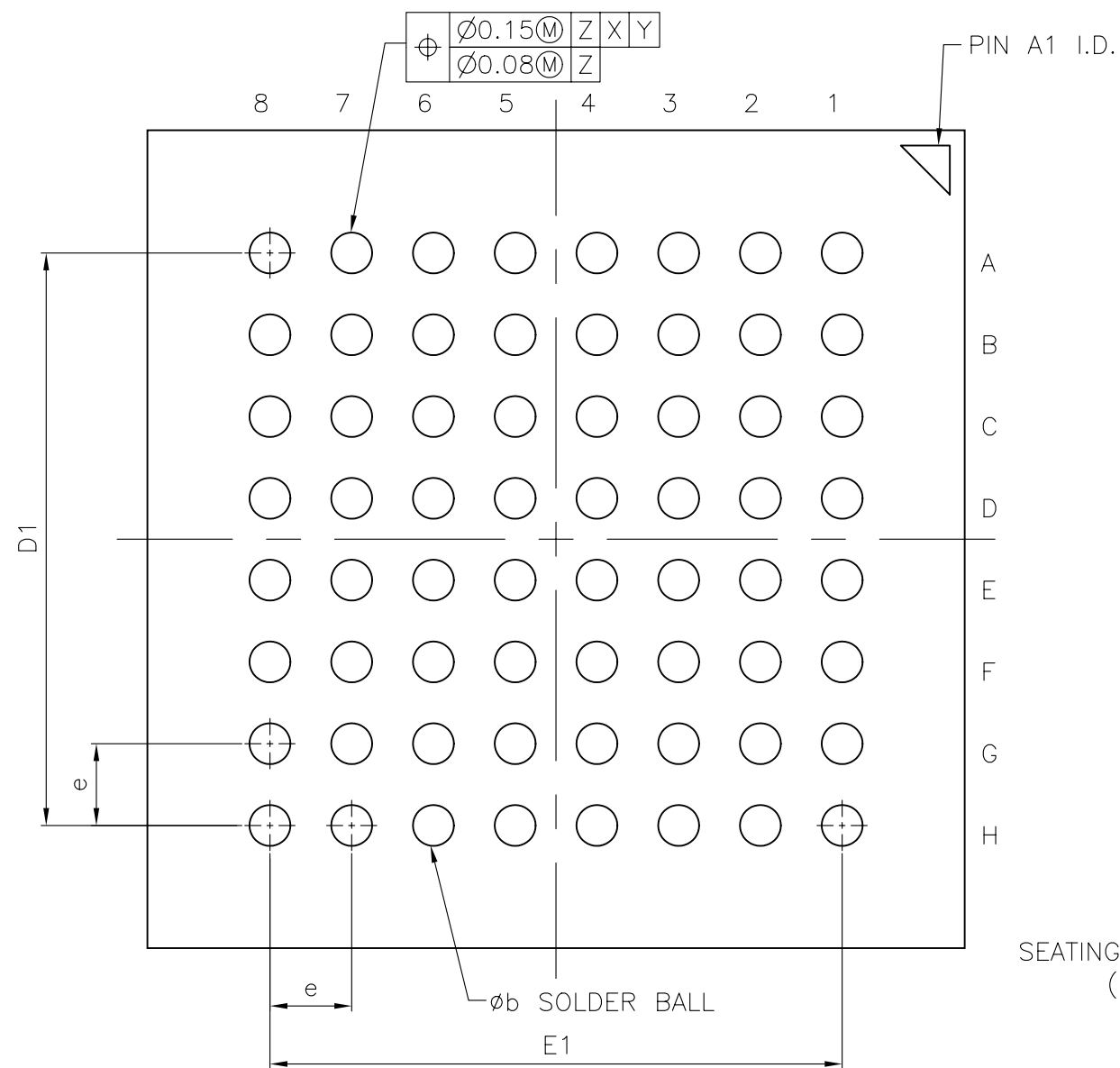
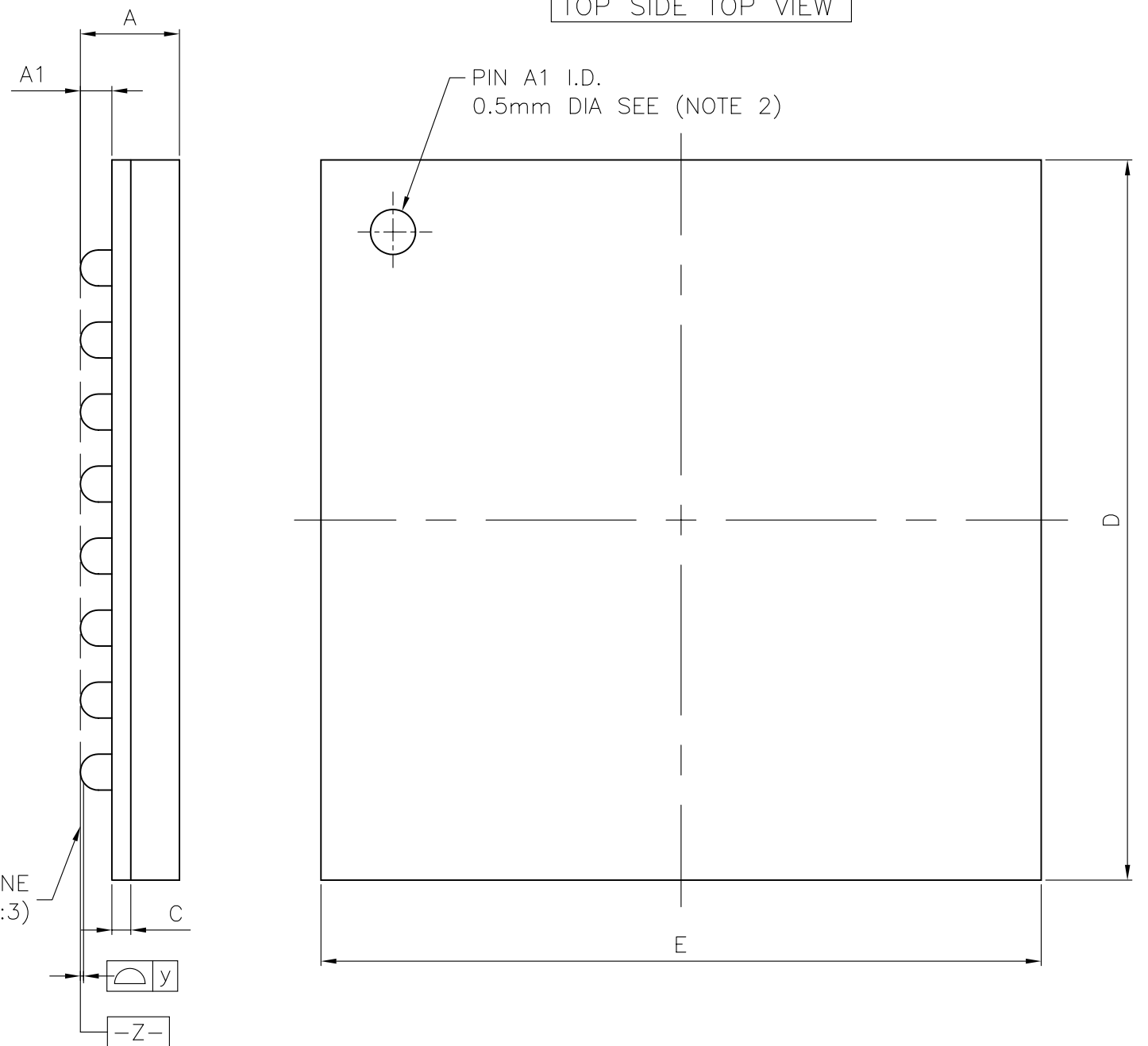


BOTTOM SIDE BOTTOM VIEW



TOP SIDE TOP VIEW



NOTE :

1. ALL DIMENSION ARE IN MILLIMETERS.
2. PIN A1 ID. TO BE MARKED BY LASER.
3. PRIMARY DATUM [-Z-] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. "e" REPRESENTS THE MAXIMUM SOLDER BALL GRID PITCH.
5. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL PITCH. PARALLEL TO PRIMARY DATUM [-Z-].

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	0.90	—	1.10
A1	0.25	—	0.35
øb	0.35	0.40	0.45
c	—	0.21	—
D	7.90	8.00	8.10
D1	5.50	5.60	5.70
E	7.90	8.00	8.10
E1	5.50	5.60	5.70
e	—	0.80	—
y	0.00	—	0.10

CUSTOMER :		LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z PRECISION IND., LTD. TAICHUNG., TAIWAN. R. O. C TITLE: MINI BGA 64L(8x8mm) PACKAGE OUTLINE DRAWING
APPROVED BY	DATE	
DRAW BY: <i>Sandy Sue</i>	07/13/05	
CHECK BY: <i>S. S. Lin</i>	07/14/05	
APPROVAL: <i>Kevin Liao</i>	07/14/05	
APPROVAL: <i>Jack Tu</i>	07/14/05	

DWG. NO.	PO-MBGA-017	REV.	0
UNIT :	mm	SCALE :	15/1
		SHEET	1 OF 1